

EXTREME PERFORMANCE HIGH-DENSITY ARRAYS

(0.80 mm) .0315" x (1.80 mm) .071" PITCH



- 4.0 Tbps aggregate data rate 9 IEEE, 400 G channels
- Extremely low crosstalk to 40 GHz+
- Incredibly tight impedance control
- Minimal variance in data rate as stack height increases
- 40% less space vs traditional arrays with the same data throughout







High-speed mezzanine connector and cable in one product family



BGA attach to board for greater density and optimized trace breakout region



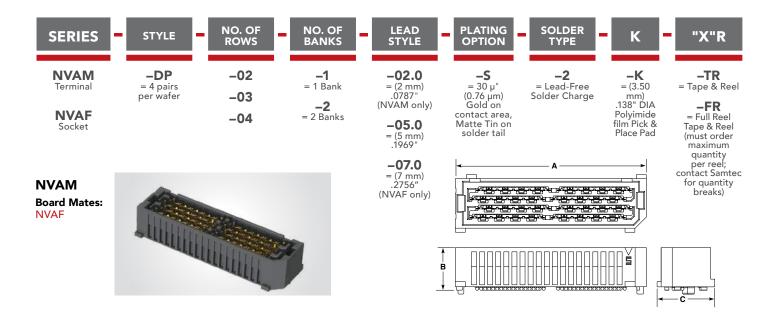
Guaranteed two points of contact to ensure a more reliable connection

KEY SPECIFICATIONS

STACK HEIGHTS	TOTAL PAIRS	INSULATOR MATERIAL	CONTACT MATERIAL	PLATING	CURRENT RATING	WORKING VOLTAGE	LEAD-FREE SOLDERABLE
7 mm, 9 mm, 10 mm & 12 mm	Up to 32 pairs	Black LCP	Copper Alloy	Au or Sn over 50 μ" (1.27 μm) Ni	2.1 A per pin (signal) 9.6 A per pin (ground)	200 VAC	Yes



0.80 mm x 1.80 mm PITCH • EXTREME PERFORMANCE ARRAYS



View complete specifications at: samtec.com?NVAM

NO. OF

-2

A (21.75)

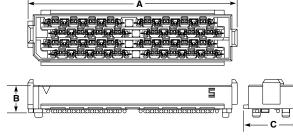
.856

(37.75)

1.486

NVAF Board Mates: NVAM





NO. OF BANKS	A
-1	(20.25) .797
-2	(36.25) 1.427

(4.80)

.189

.268

LEAD STYLE

-05.0

-07.0

NO. OF

-02

-0.3

-04

c

(7.80)

.307

(9.60)

.378

.449

В

(5.46)

.215

(8.46)

.333

-02.0

-05.0

MATED HEIGHTS*					
	NVAM LEAD STYLE				
NVAF LEAD STYLE	-02.0	-05.0			
-05.0	(7.00) .276	(10.00) .394			
-07.0	(9.00) .354	(12.00) .472			

AGGREGATE DATA RATE (NRZ)						
448 Gbps	672 Gbps	89 Gb		1344 Gbps	1792 Gbps	
1 Bank		2 Bank				
2 Row	3 Row	4 Row	2 Row	3 Row	4 Row	
8 Pairs	12 Pairs	16 Pairs		24 Pairs	32 Pairs	

NO. OF ROWS	с
-02	(6.00) .236
-03	(7.80) .307
-04	(9.60) 378

Notes:

Some sizes, styles and options are non-standard, non-returnable

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^{*}Processing conditions will affect mated height.